

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	523	(210/748.ccls. or 210/243.ccls. or 210/198.1.ccls. or 210/205.ccls. or 210/757.ccls.) and electrode and (metal or copper) and (plat\$3 or deposit\$3)	US-PGPUB; USPAT	OR	ON	2005/01/10 12:42
L2	276	(210/748.ccls. or 210/243.ccls. or 210/198.1.ccls. or 210/205.ccls. or 210/757.ccls.) and electrode and ((metal or copper) same ion\$5) and (plat\$3 or deposit\$3)	US-PGPUB; USPAT	OR	ON	2005/01/10 12:52
L3	905	(210/748.ccls. or 210/243.ccls. or 210/198.1.ccls. or 210/205.ccls. or 210/757.ccls.) and electrode	US-PGPUB; USPAT	OR	ON	2005/01/10 12:44
L4	276	3 and ((metal or copper) same ion\$5) and (plat\$3 or deposit\$3)	US-PGPUB; USPAT	OR	ON	2005/01/10 12:45
L5	168	3 and ((metal or copper) same ion\$5) and ((plat\$3 or deposit\$3) same electrode)	US-PGPUB; USPAT	OR	ON	2005/01/10 12:46
L6	207	(210/748.ccls. or 210/243.ccls. or 210/198.1.ccls. or 210/205.ccls. or 210/757.ccls. or 210/900.ccls.) and ((metal or copper) same ion\$5) and ((plat\$3 or deposit\$3) same (electrode or anode or cathode))	US-PGPUB; USPAT	OR	ON	2005/01/10 13:39
L7	39	(134/1.3.ccls. or 134/902.ccls.) and ((metal or copper) same ion\$5) and ((plat\$3 or deposit\$3) same (electrode or anode or cathode))	US-PGPUB; USPAT	OR	ON	2005/01/10 13:44
L8	206	((205/750) or (205/771) or (205/772)).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/01/10 13:45
L9	83	(205/750.ccls. or 205/771.ccls. or 205/772.ccls.) and ((plat\$3 or deposit\$3) same (electrode or anode or cathode)) and (ion\$5 or wafer or substrate)	US-PGPUB; USPAT	OR	ON	2005/01/10 14:04
L10	250	(204/275.1.ccls.) and ((plat\$3 or deposit\$3) same (electrode or anode or cathode)) and (ion\$5 or wafer or substrate)	US-PGPUB; USPAT	OR	ON	2005/01/10 14:04
L11	190	(204/275.1.ccls.) and ((plat\$3 or deposit\$3) same (electrode or anode or cathode)) and ((ion\$5 or wafer or substrate) same (metal or copper))	US-PGPUB; USPAT	OR	ON	2005/01/10 14:04

L12	111	(204/275.1.ccls.) and ((plat\$3 or depost\$3) same (electrode or anode or cathode)) and ((ion\$5 or wafer or substrate) same (metal or copper)) and (cleaning or hydrochloric or suphuric or sulfuric)	US-PGPUB; USPAT	OR	ON	2005/01/10 14:05
L13	47	(204/275.1.ccls.) and ((plat\$3 or depost\$3) same (electrode or anode or cathode)) and ((ion\$5) same (metal or copper)) and (cleaning or hydrochloric or suphuric or sulfuric) and (substrate or wafer or semiconductor)	US-PGPUB; USPAT	OR	ON	2005/01/10 14:14
L14	70	((plat\$3 or depost\$3) and (electrode or anode or cathode)) and ((ion\$5) and (metal or copper or cu)) and (cleaning or hydrochloric or suphuric or sulfuric or hcl) and (substrate or wafer or semiconductor)	EPO; JPO; DERWENT	OR	ON	2005/01/10 14:14